

HD MEZZ™ ARRAY SOCKET HDAF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDAF

- Insulator Material:** Black Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Current Rating:** Testing Now!
- Operating Temp Range:** -55°C to +125°C
- Plating:** Au or Sn over 50µ" (1.27µm) Ni
- Contact Resistance:** Testing Now!
- Working Voltage:** Testing Now!
- Mated Cycles:** Testing Now!

Processing:

- Max Processing Temp:** 230°C for 60 seconds with Type -1 solder crimp, or 230°C for 60 seconds, or 260°C for 20 seconds 3x with Type -2 solder crimp
- Lead-Free Solderable:** Type -1: No
Type -2: Yes

Mates with:
HDAM

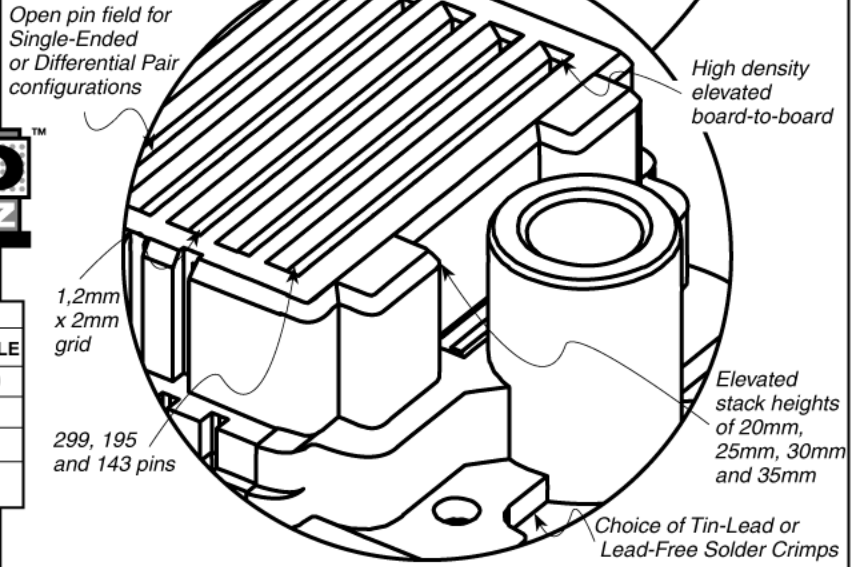


MATED HEIGHTS*		
HDAF LEAD STYLE	HDAM LEAD STYLE	
-08.0	20mm	30mm
-18.0	25mm	35mm

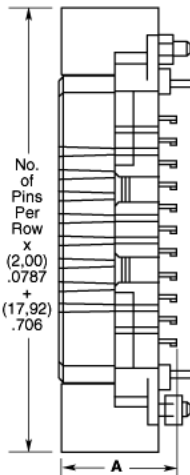
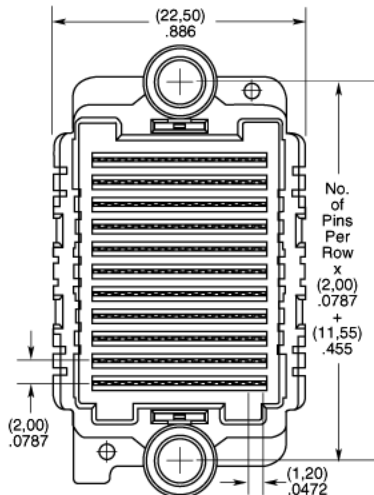
*Processing conditions will affect mated height.

*HD Mezz™ is a trademark of Molex, Inc.

Open pin field for Single-Ended or Differential Pair configurations



HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76µm) Gold on contact area, Matte Tin on tails and guide pins	-13	-1 = 63% Sn/37% Pb Solder Crimp -2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Crimp	-P = Pick & Place Pad



LEAD STYLE	A
-08.0	(10,51) .414
-18.0	(20,51) .807

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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